

DESCRIPTION

The GLF2351A is an advanced technology fully integrated power switch for applications required for precision output current limiting. The GLF2351A also features various protection functions such as under voltage lockout, true reverse current blocking (TRCB), short circuit protection, and thermal shutdown.

The GLF2351A provides a built-in output voltage slew rate control to limit the inrush current and voltage surges. The FLGB output pin can be used to send a signal of fault events to the system controller. The integrated thermal shutdown (TSD) insures complete protection for the switch during output current limit and short circuit conditions. The GLF2351A is an ideal switch for USB power supply.

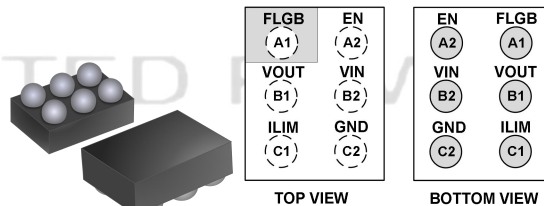
FEATURES

- Input Range: 2.5 V to 5.5 V
- Programmable Output Constant Current Limit
Range: 40 mA to 2.8 A
- Low R_{ON} : 32 m Ω Typ. at 5.0 V_{IN}
- Ultra-Low I_Q : 19 μ A Typ. at 5.0 V_{IN}
- Ultra-Low I_{SD} : 63 nA Typ. at 5.0 V_{IN}
- Under Voltage Lockout Protection
- Output Voltage Slew Rate Controlled
- True Reverse Current Blocking Protection
- Short Circuit Protection
- Deglitched Fault Flag Indication
- Integrated Output Discharge Switch
- Thermal Shutdown Protection

APPLICATIONS

- Notebooks and Tablets
- Wireless LAN and Broadband Access Devices
- Storage and Peripherals
- Smart Mobile Devices

PACKAGE



0.97 mm x 1.47 mm x 0.55 mm WL-CSP 0.5 mm Pitch

DEVICE ORDERING INFORMATION

Part Number	Top Mark	Current Limit ILIM	Output Discharge	Fault Flag FLGB	EN Activity	Package
GLF2351A-S3G7	JG	Programmable 40 mA to 2.8 A	300 Ω	Yes	High	0.97 mm x 1.47 mm CSP

APPLICATION DIAGRAM

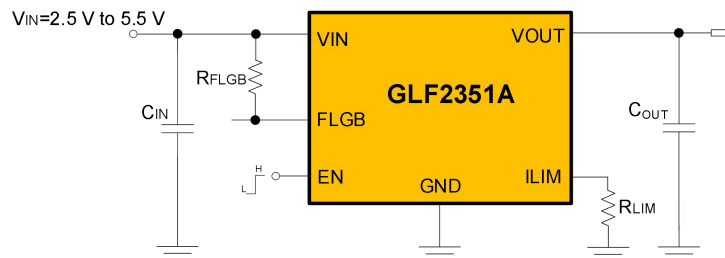


Figure 1. Typical Application

FUNCTIONAL BLOCK DIAGRAM

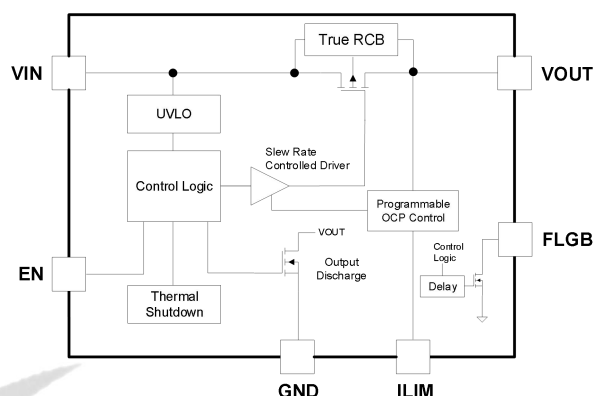
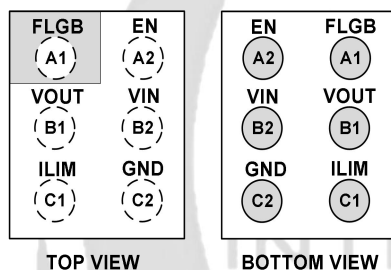


Figure 2. Functional Block Diagram

PIN CONFIGURATION



PIN DEFINITION

Pin #	Name	Description
A1	FLGB	Flag pin goes low to indicate OCP, SC, TRCB, UVLO and TSD fault conditions
A2	EN	Active high switch output enables the device
B1	VOUT	Switch output
B2	VIN	Switch Input. Supply voltage for IC
C1	ILIM	Programmable current limit Do not leave this pin floating.
C2	GND	Ground

Figure 3. Package and Pin configuration

ABSOLUTE MAXIMUM RATINGS

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit
V_{IN}	V_{IN} , V_{OUT} , V_{EN} to GND	- 0.3	6	V
I_{OUT}	DC Continuous Current at $T_A = 25^{\circ}\text{C}$		3	A
T_J	Junction Temperature		150	$^{\circ}\text{C}$
T_{STG}	Storage Junction Temperature	- 65	150	$^{\circ}\text{C}$
θ_{JA}	Thermal Resistance, Junction to Ambient		120	$^{\circ}\text{C}/\text{W}$
ESD	Electrostatic Discharge Capability	Human Body Model, JESD22-A114	8	kV
		Charged Device Model, JESD22-C101	2	

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min.	Max.	Unit
V_{IN}	Supply Voltage	2.5	5.5	V
T_A	Ambient Operating Temperature	-40	+85	$^{\circ}\text{C}$

ELECTRICAL CHARACTERISTICS

Values are at $V_{IN} = 5.0\text{ V}$ and $T_A = 25\text{ }^{\circ}\text{C}$. Unless otherwise noted

Symbol	Parameter	Conditions		Min.	Typ.	Max.	Units
Basic Operation							
I _Q	Quiescent Current	V _{EN} = High, I _{OUT} =0 mA, V _{IN} = V _{EN} =5.0V			19	25	μA
		V _{EN} = High, I _{OUT} =0 mA, V _{IN} = V _{EN} =5.0V, T _A =85 °C			26		
I _{SD}	Shutdown Current	V _{EN} = Low, V _{IN} =5.0 V			63	100	nA
		V _{EN} = Low, V _{IN} =5.0 V, T _A =85 °C			660		
R _{ON}	On-Resistance	V _{IN} =5.0 V, I _{OUT} = 500 mA	T _A =25 °C		32	42	mΩ
			T _A =85 °C ⁽¹⁾		40		
		V _{IN} =2.5 V, I _{OUT} = 500 mA	T _A =25 °C		46	56	
			T _A =85 °C ⁽¹⁾		56		
R _{DSC}	Output Discharge Resistance	V _{EN} = Low, I _{FORCE} = 10 mA			300		Ω
V _{IH}	EN Input Logic High Voltage	V _{IN} = 2.5 V to 5.5 V		1.2			V
V _{IL}	EN Input Logic Low Voltage	V _{IN} = 2.5 V to 5.5 V				0.6	V
R _{EN}	EN pull down resistance	Internal Resistance			10		MΩ
I _{EN}	EN Source or Sink Current	V _{EN} = 5.5 V				0.6	μA
V _{FLGB}	FLGB Output Low Voltage	I _{FLGB} = 0.5 mA				100	mV
I _{FLGB}	FLGB Output High Leakage	V _{FLGB} = 5.5 V				50	nA
t _{FLAG}	FLGB Output Delay Time ⁽¹⁾	Delay time for assertion at over-current			8		ms
		Delay time for assertion at short circuit and thermal shutdown conditions			120		μs
Protection							
V _{UVLO}	Under Voltage Lockout Voltage	Input Rising			2.4		V
		Input Falling			2.1		
I _{LIM}	Over Current Limit ⁽¹⁾	R _{LIM} = 1 kΩ		2.5	2.8	3.1	A
V _{RCB_TH}	Reverse Current Blocking Protection Trip Voltage	V _{OUT} - V _{IN}			25		mV
V _{RCB_RL}	Reverse Current Blocking Protection Release Voltage	V _{IN} - V _{OUT}			23		
I _{RCB}	Reverse Current Blocking Protection Leakage	V _{OUT} – V _{IN} > V _{RCB}				1	μA
TSD	Thermal Shutdown	20 °C Hysteresis ⁽¹⁾			140		°C
Switching Characteristics ⁽²⁾							
t _{dON}	Turn-On Delay	R _{OUT} = 150 Ω, C _{OUT} = 1.0 μF			106		μs
t _R	V _{OUT} Rise Time				486		
t _{dOFF}	Turn-Off Delay	R _{OUT} = 150 Ω, C _{OUT} = 1.0 μF			17		
t _F	V _{OUT} Fall Time				220		

Notes: 1. By design; characterized; not production tested. 2. Switching Timing Diagram

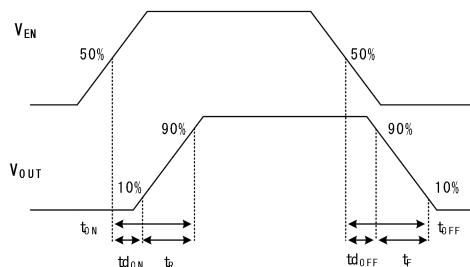


Figure 4. Switching Timing Diagram

TYPICAL PERFORMANCE CHARACTERISTICS

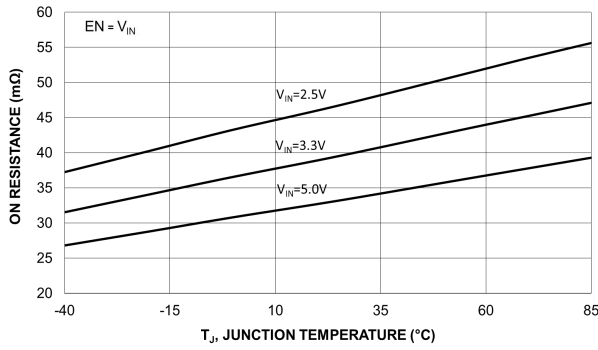


Figure 5. On-Resistance vs. Temperature

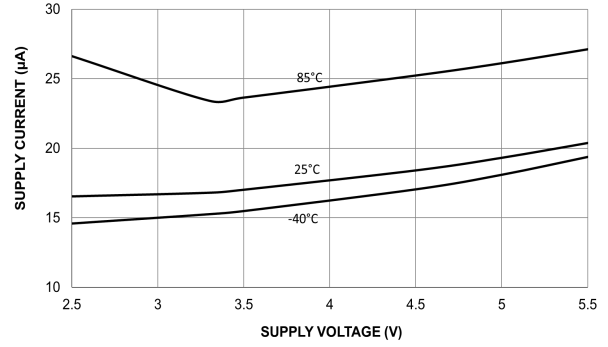


Figure 6. Quiescent Current vs. Supply Voltage

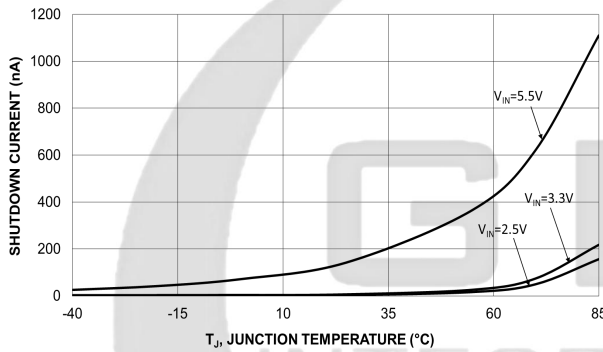


Figure 7. Shutdown Current vs. Temperature

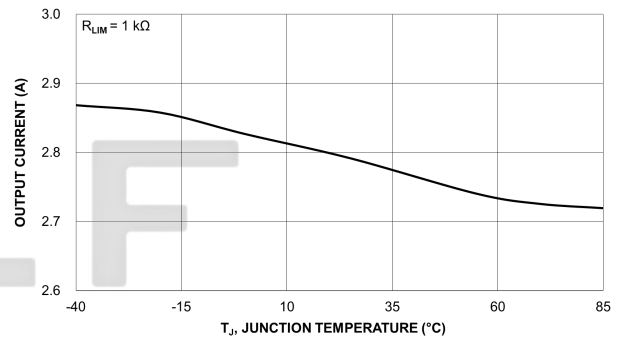


Figure 8. Over Current Limit vs. Temperature

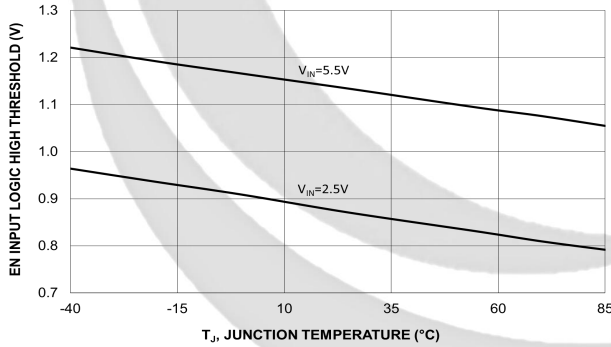


Figure 9. EN Input Logic High Threshold

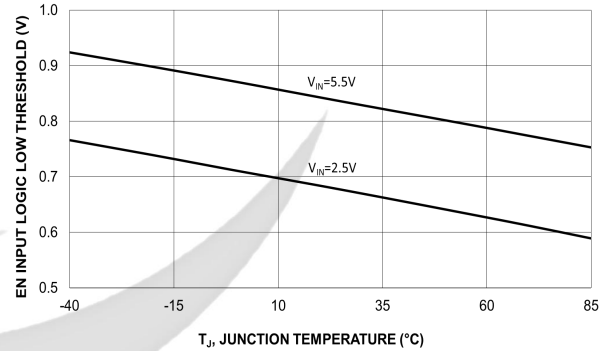


Figure 10. EN Input Logic Low Threshold

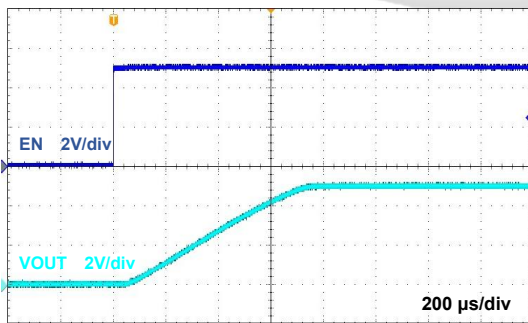


Figure 11. Turn-On Response
 $V_{IN}=5.0\text{ V}$, $C_{IN}=C_{OUT}=1.0\text{ }\mu\text{F}$, $R_L=150\text{ }\Omega$

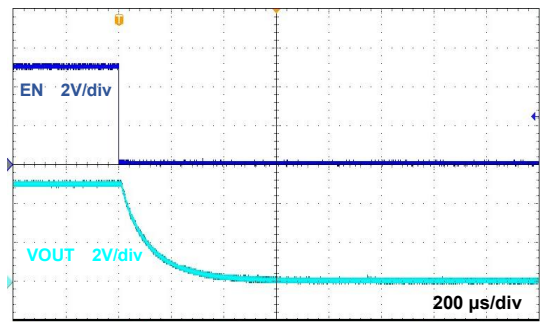


Figure 12. Turn-Off Response
 $V_{IN}=5.0\text{ V}$, $C_{IN}=C_{OUT}=1.0\text{ }\mu\text{F}$, $R_L=150\text{ }\Omega$

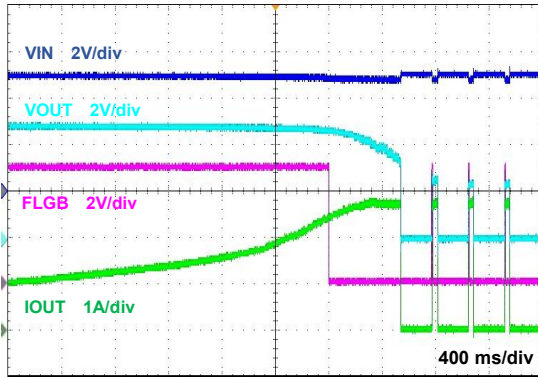


Figure 13. Current Limit Response
 $V_{IN}=5.0\text{ V}$, $C_{IN}=C_{OUT}=1.0\text{ }\mu\text{F}$

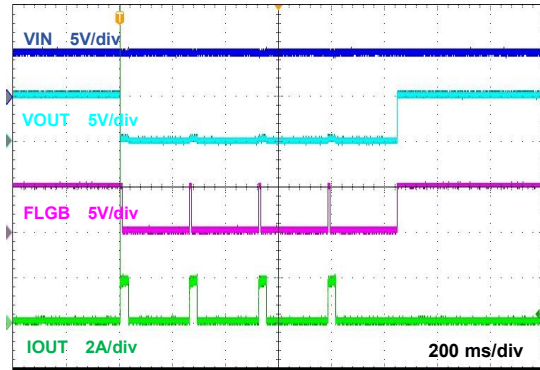


Figure 14. Short Circuit Response
 $V_{IN}=5.0\text{ V}$, $C_{IN}=C_{OUT}=1.0\text{ }\mu\text{F}$, $R_L=0\text{ }\Omega$

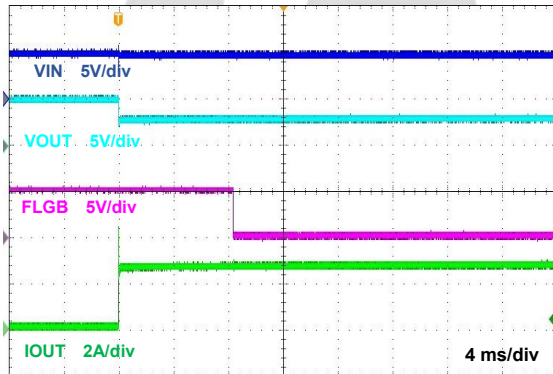


Figure 15. FLGB Response
 $V_{IN}=5.0\text{ V}$, $C_{IN}=C_{OUT}=1.0\text{ }\mu\text{F}$

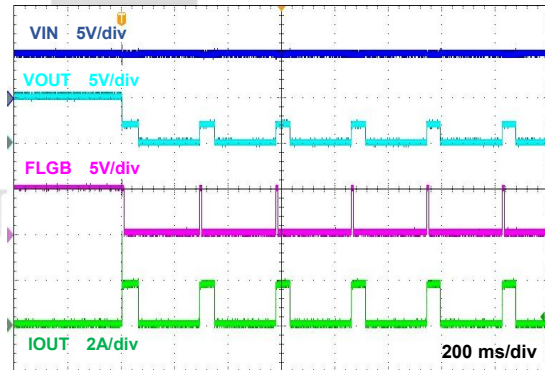


Figure 16. OTP Response
 $V_{IN}=5.0\text{ V}$, $C_{IN}=C_{OUT}=1.0\text{ }\mu\text{F}$

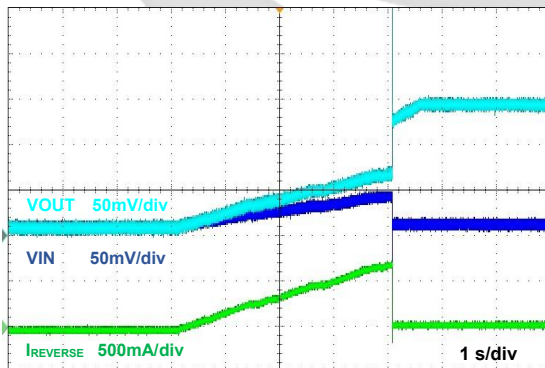


Figure 17. Reverse Current Blocking Threshold
 $V_{IN}=3.3\text{ V}$, $V_{OUT}=\text{Up to }3.4\text{ V}$, $C_{IN}=C_{OUT}=1.0\text{ }\mu\text{F}$

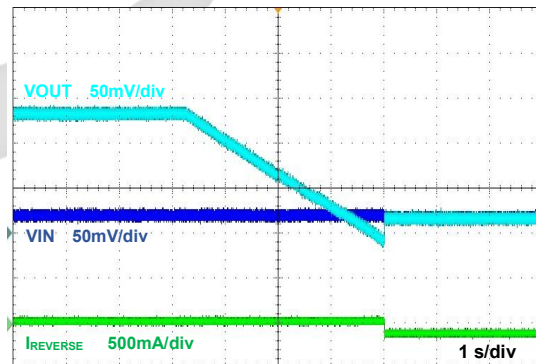


Figure 18. Reverse Current Blocking Release
 $V_{IN}=3.3\text{ V}$, $V_{OUT}=\text{Down to }3.3\text{ V}$, $C_{IN}=C_{OUT}=1.0\text{ }\mu\text{F}$

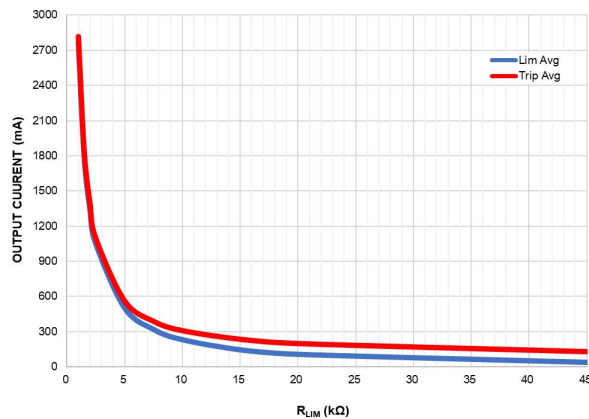
APPLICATION INFORMATION

The GLF2351A is an advanced technology fully integrated power switch for applications required for precision output current limiting. It also features various protection functions such as under voltage lockout, true reverse current blocking (TRCB), short circuit protection, and thermal shutdown protection.

Current Limiting and Over Temperature Protection

When the GLF2351A is enabled, the current-limit circuitry starts monitoring the output current. When the load current reaches up to the over current protection threshold or short circuit occurs, the device clamps the output current to a preset constant current limit level by an external resistor (R_{LIM}) between ILIM and GND pins. The 1% precision resistors are recommended. The R_{LIM} resistor traces should be as short as possible to reduce parasitic effects on the current-limit accuracy. Refer to the Figure 19 and table 1 to find the resistor values corresponding to different current limit levels. When the load current back to normal and the short circuit condition is removed, the device releases the clamped output current.

When the current limit condition continues and the junction temperature exceeds the exceeds the OTP (Over Temperature Protection) threshold, 140 °C, the GLF2351A is turned off immediately. As the junction temperature cools down below the OPT hysteresis, the GLF2351A resumes normal operation.



R_{LIM} (kΩ)	Current Limit Trip Typ (mA)			Current Limit Typ (mA)		
	Min	Typ	Max	Min	Typ	Max
1.0	2625	2940	3255	2500	2800	3100
1.5	1701	1890	2079	1620	1800	1980
2.0	1260	1418	1565	1200	1350	1490
2.5	998	1103	1208	950	1050	1150
5.0	495	560	605	450	500	550
7.5	348	384	420	290	320	350
10	240	310	380	205	230	255
15	155	234	315	130	145	160
20	120	198	280	100	110	120
45	60	130	200	20	40	60

Figure 19. Current Trip and Limit vs. R_{LIM}

Table 1. Current Limit Level by R_{LIM}

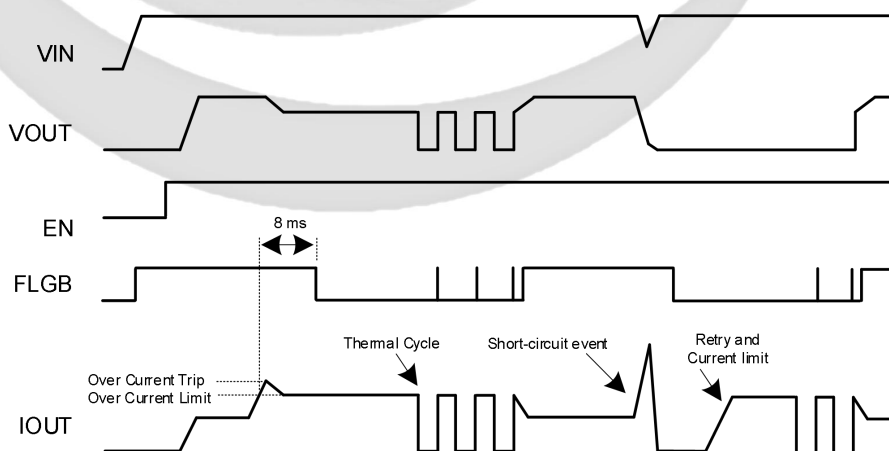


Figure 20. Over Current and Short Circuit Protection

True Reverse Current Blocking

The GLF2351A has a built-in reverse current blocking protection which always monitors the output voltage level regardless of the status of EN pin to check if it is greater than the input voltage (V_{RCB_TH}). When the output voltage goes beyond the input voltage by the reverse current blocking protection trip voltage (V_{RCB_RL}), the GLF2351A is turned off. Note that some reverse current can occur until the V_{RCB_TH} is triggered. The main switch will resume normal operation when the output voltage drops below the input source by the RCB protection release voltage.

Fault Flag Response

The output of the open drain FLGB pin goes active low for any of following fault conditions: output current limit, output short-circuit, reverse current blocking, or thermal shutdown. The GLF2351A is designed to avoid false FLGB reporting by using an internal 8 ms deglitch delay for the current limit condition and 120 μ s delay for the short circuit and over temperature conditions. The FLGB output remains low until over-current or over-temperature condition is removed. When short circuit fault conditions occur, the device limits the output current and the FLGB output remains low. The FLGB signal is de-asserted once device power is cycled or the enable is toggled and the device resumes normal operation.

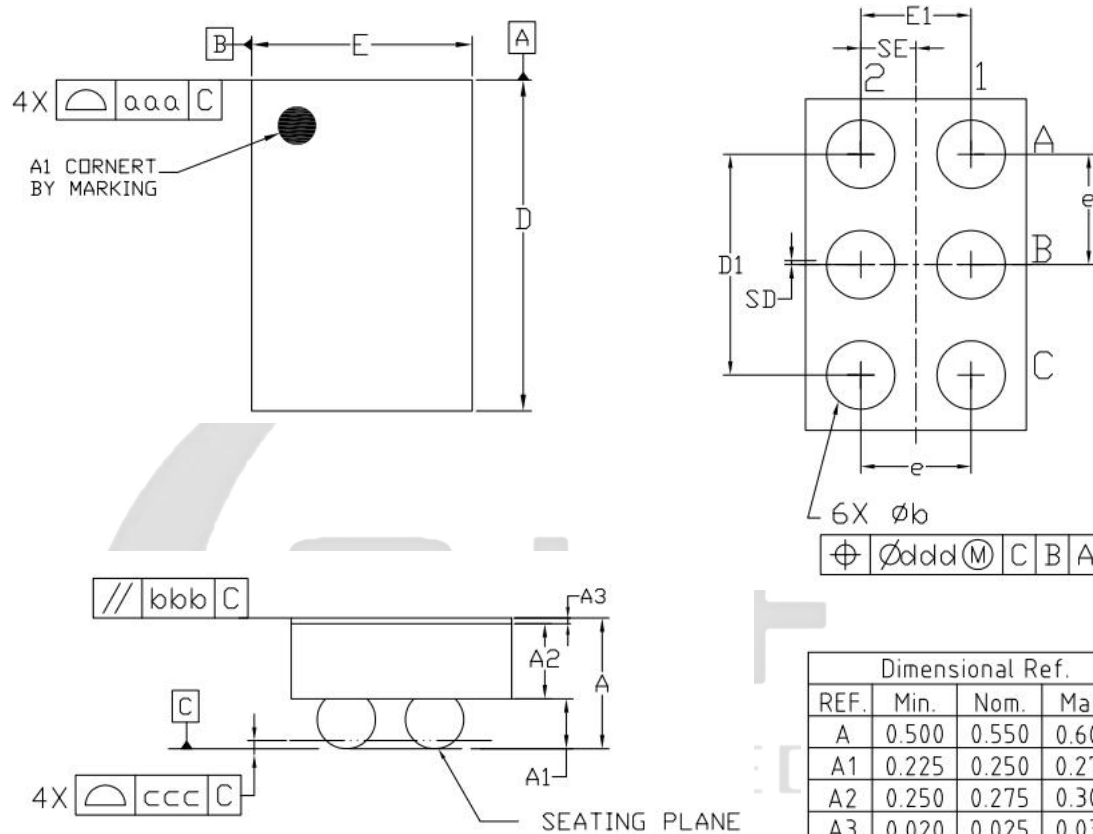
EN pin

The GLF2351A can be activated by EN pin high. Note that the EN pin has an internal pull-down resistor to maintain a reliable status without EN signal applied from an external controller.

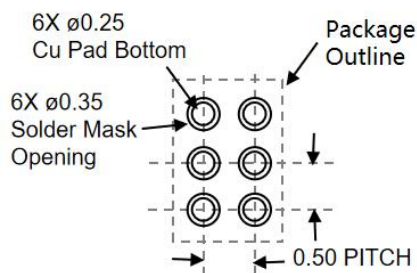
Input and Output Capacitor

A minimum 1 μ F input capacitor is recommended to be placed close to the V_{IN} pin to reduce the voltage drop on the input power rail caused by transient inrush current at start-up. A higher input capacitor value can be used to further attenuate the input voltage drop. Also, a minimum 1 μ F output capacitor is recommended to minimize voltage undershoot on the output pin during the transition when the switch is turned off. Undershoot can be caused by parasitic inductance from board traces or intentional load inductances. If load inductances do exist, use of an output capacitor can improve output voltage stability and system reliability. The C_{OUT} capacitor should be placed close to the VOUT and GND pins.

PACKAGE OUTLINE



Recommended Footprint



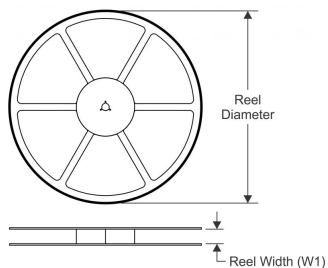
Dimensional Ref.			
REF.	Min.	Nom.	Max.
A	0.500	0.550	0.600
A1	0.225	0.250	0.275
A2	0.250	0.275	0.300
A3	0.020	0.025	0.030
D	1.460	1.470	1.485
E	0.960	0.970	0.985
D1	0.950	1.000	1.050
E1	0.450	0.500	0.550
b	0.260	0.310	0.360
e	0.500 BSC		
SD	0.000 BSC		
SE	0.250 BSC		
Tol. of Form&Position			
aaa	0.10		
bbb	0.10		
ccc	0.05		
ddd	0.05		

Notes

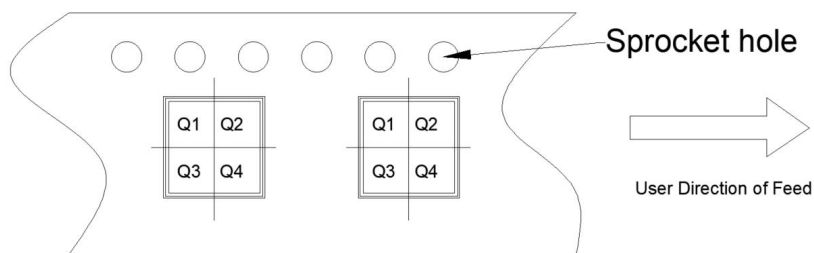
1. ALL DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGRESS)
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.
3. A3: BACKSIDE LAMINATION

TAPE AND REEL INFORMATION

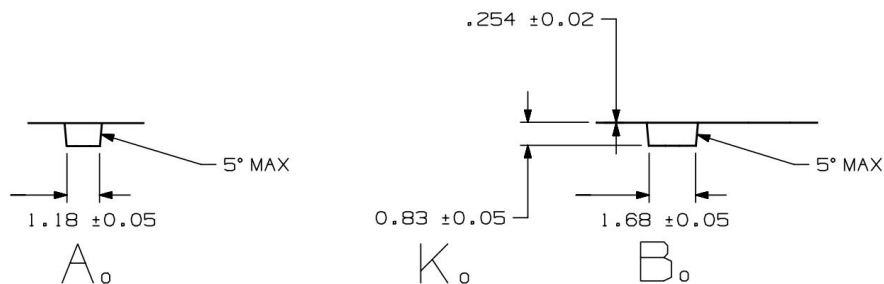
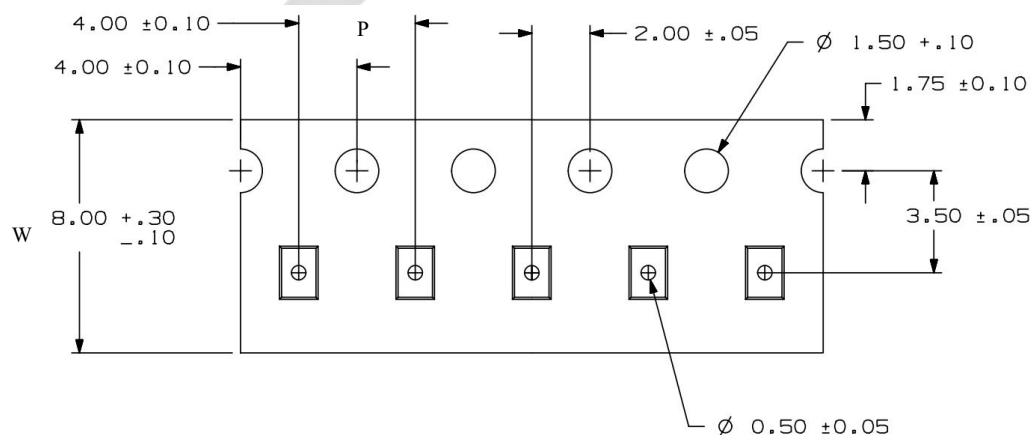
REEL DIMENSIONS



QUADRANT ASSIGNMENTS PIN 1 ORIENTATION TAPE



TAPE DIMENSIONS



Device	Package	Pins	SPQ	Reel Diameter (mm)	Reel Width W1	A0	B0	K0	P	W	Pin1
GLF2351A-S3G7	WLCSP	6	3000	180	9	1.18	1.68	0.83	4	8	Q1

Remark:

A0: Dimension designed to accommodate the component width

B0: Dimension designed to accommodate the component length

C0: Dimension designed to accommodate the component thickness

W: Overall width of the carrier tape

P: Pitch between successive cavity centers

SPECIFICATION DEFINITIONS

Document Type	Meaning	Product Status
Target Specification	This is a target specification intended to support exploration and discussion of critical needs for a proposed or target device. Spec limits including typical, minimum, and maximum values are desired, or target, limits. GLF reserves the right to change limits at any time without warning or notification. A target specification in no way guarantees future production of the device in question.	Design / Development
Preliminary Specification	This is a draft version of a product specification. The specification is still under internal review and subject to change. GLF reserves the right to change the specification at any time without warning or notification. A preliminary specification in no way guarantees future production of the device in question.	Qualification
Product Specification	This document represents the anticipated production performance characteristics of the device.	Production

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